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**ELECTRONICS GO 3D –
FROM PRINTED ELECTRONICS TO 3D STRUCTURAL ELECTRONICS –
STATUS AND ROADMAP FOR NEW COMPACT 3D FUNCTIONAL APPLICATIONS**

Thin, light, compact, inexpensive and free in shape and surface, these are the requirements for electronics in future products in the automotive industry, household appliances and devices and products in medical applications.

Printed electronics already play an increasing role in the implementation of these requirements. Special requirements are placed on adhesives for integration.

The lecture introduces the state of the art, from realized and planned applications to the technology roadmap of the OE-A (freshly presented in the 8th edition)